



* does not represent
actual color

Sil25-RXP Form-In-Place

A single component, non-slump, high flexibility, room temperature silicone gasket material.

Laird Technologies' Form-In-Place is an automated system for dispensing non-conductive and conductive elastomer EMI shielding and grounding gaskets onto metal substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, and mobile phones, as well as many other cast enclosures and packaged electronic assemblies.

TYPICAL VALUES

MATERIAL PROPERTIES	TEST METHOD	Sil25-HXP
Product Type		Single Component Silicone
Color		White
Density, g/cm ³		1.2
Hardness, Shore A		25
Tensile Strength, MPa	ASTM D412	4.5
Compression Set, 22 Hrs, 23°C, 25% Compression	ASTM D575	<20
Adhesion (Al), N/cm ²	LT-FIP-CLE-03	220
Time to skin @ 23°C, 50% RH		10 – 25 minutes
Cure @ 23°C, 50% RH		12 hours per mm thick

Information on the product described is based on laboratory test data which Laird Technologies believes to be reliable. It is recommended that each user make their own tests to determine the suitability of Laird Technologies' products for their application.

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EMI-FIP-DS-Sil25-RXP 0710

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